



Call for Papers

Zurich, Switzerland, 21–22 March 2012
smartsystemsintegration.com



Co-organizer:



Part of the activities of:



Invitation SSI 2012

Smart systems provide novel enabling functionalities and as such are currently a driving force behind product innovation. For that reason they are crucial for the competitiveness of companies and entire industry sectors like aeronautics, automotive, security, logistics and other. Moreover smart systems development will support solving big challenges of mankind, such as socio-economic problems in health, environment, mobility and other domains.

Smart systems will be networked, energy autonomous, miniaturized, reliable and sometimes even implantable. They are becoming increasingly complex, consist of different components and they involve different technologies and materials.

With the Smart Systems Integration Conference 2012 (SSI) we will show a snapshot of the current smart applications and international research work related to smart technology, smart materials, smart energy, smart mobility and 3D integration. There will be special sessions related to best practice examples and the strategy of the European Platform on Smart Systems Integration (EPoSS). A second special session focuses on actual industrial and scientific developments in the USA. Additionally the European Executive Congress of the MEMS Industry Group will be held in collaboration with the SSI 2012 one day before the SSI.

On behalf of the committee, the co-chair – Dr. Günter Lugert of Siemens AG and chairman of EPoSS Steering Committee – and the local co-chairs from Switzerland – André Perret (CSEM), Nico de Rooij (EPFL), Christopher Hierold (ETH) and Gian-Luca Bona (Empa) – I look forward to receiving your application oriented and/or scientific submission.

July 2011

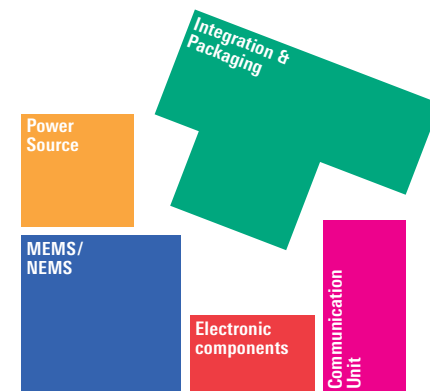
Prof. Dr. Thomas Gessner
Fraunhofer Institute for Electronic Nano Systems
Conference Chair Smart Systems Integration 2012

Conference topics 2012

1. Smart systems for automotive applications/ green car and aeronautics
2. Smart MedTech systems and systems for prognostics health management
3. Smart systems in logistics and security applications
4. Power management of smart systems/energy efficiency, energy harvesting
5. Smart communication and sensor networks/ self-sufficient sensor networks
6. Manufacturing technologies for smart system integration
7. Design of smart systems, component design and simulation
8. Micro and nano systems/embedded systems
9. Advanced micro and nano technologies
10. New materials, nano structures and devices
11. Assembly and interconnect technologies
12. System integration and packaging
13. Test and reliability of components and systems

Smart Systems Integration International Conference and Exhibition

- focuses on complex systems in consideration of the components,
- is application-oriented,
- close to the industry and
- shows the potential of research and development activities worldwide.



Become a speaker!

**Highlight your expertise
at the SSI conference
with concurrent exhibition!**

Your advantages at a glance

- Present in front of a highly qualified audience.
- Exchange your experiences with other experts.
- Build your personal network.
- Benefit from maximum attention for your presentation due to extensive press work and several advertising activities.
- Take the opportunity to win the best paper/best poster award.

Deadlines

Submission of abstracts

14 October 2011

Selection by committee

15 November 2011

Submission of full manuscripts

10 January 2012

Online submission at

www.smartsystemsintegration.com



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Committee list

Conference chair

Prof. Dr. Thomas Gessner, Fraunhofer ENAS, D

Co-chair

Dr. Günter Lugert, Siemens, EPoSS, D

Local organizing committee

Prof. Dr. Christofer Hierold, ETH, CH

Dr. André Perret, CSEM, CH

Prof. Dr. Nico de Rooij, EPFL, CH

Prof. Dr. Gian-Luca Bona, Empa, CH

Scientific committee

R. Aschenbrenner, Fraunhofer IZM, D

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J. Greer, Tyndall National Institute, IRL

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R. Zengerle, IMTEK, D

Advisory committee

International members

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J. Fjelstad, Verdant Electronics, USA

R. Grace, R. Grace Associates, USA

K. Lightman, MEMS Industry Group, USA

Z. Zhou, Tsinghua University Beijing, RC

Members of EPoSS advisory committee

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G. Müller, EADS, D

F. Mullany, Alcatel-Lucent, IRL

R. Neul, Bosch, D

A. Nguyen-Dinh, Vermon, F

P. Perlo, CRF, I

A. Ripart, Sorin Group, F

Submission requirements

Conference language

English

Submission no later than 14 October 2011

at www.smartsystemsintegration.com

Conditions of acceptance

Authors are expected to secure the registration of 295 EUR + VAT as well as travel and accommodation funding through their sponsoring organizations, before submitting abstracts. Full payment will be due once the submission has been accepted. Only original material should be submitted.

Government and company clearance to present and publish should be finalized at the time of submission. Non-research based papers which attempt to promote commercial products cannot be submitted.

Selection process

The committee will review all submitted abstracts to maintain the high quality of the conference. Only papers submitted on time and addressing subjects which are topical and relevant to the conference will be considered for inclusion in the conference programme. Submitted papers may be selected for oral or poster presentation.

Venue

Following Paris, Barcelona, Brussels, Como and Dresden, the 2012 event will be held in Zurich, Switzerland. The World Trade Center Zurich is located in the North of Zurich just a few tram stops away from the historic old town and the lake Zurich. Zurich has excellent flight and railway connections. www.wtc-zurich.ch

Oral and poster presentations

Oral presentations will be held in different sessions. The duration of each presentation should not exceed 25 minutes including 5 minutes for subsequent discussions. Poster authors will have the opportunity to present their posters during a special poster session and throughout the conference. All oral and poster presentations will be included in the conference proceedings.

Tutorials

Tutorials are designed to provide in-depth knowledge on special topics. They should include hands-on activities or demonstrations, illustrated by means of examples and widely agreed solutions. Tutorials can be led by one or more speakers and should not exceed 3 hours.

Impressions of the SSI 2011 Exhibition and Conference in Dresden, Germany

